

ABSTRACT

A cooling device for a heat-generating electronic component such as a semiconductor integrated circuit element 5 is provided. In particular, a cooling device using a thermoelectric conversion material is provided. A cooling device for an electronic component includes a thermoelectric conversion material disposed between two electrodes that function as a cathode and an anode and are electrically 10 short-circuited. The thermoelectric conversion material is either a p-type material or an n-type material or a combination of p-type and n-type materials arranged alternately in series. This cooling device is brought into contact with an electronic component requiring cooling so 15 that one electrode side in contact with the thermoelectric conversion material becomes a low-temperature side and the other electrode side becomes a high-temperature side. A temperature difference between the two electrodes causes the thermoelectric conversion material to produce a 20 thermoelectromotive force which generates current to cool the high-temperature side.